



Material Content Data Sheet



Sales Product Name	BAR 89-02LRH E6327			Issued		29. August 2013		
MA#	MA000241006							
Package	PG-TSLP-2-7			Weight*		0.52 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.12		1201	
	noble metal	gold	7440-57-5	0.002	0.47		4660	
	inorganic material	silicon	7440-21-3	0.029	5.69	6.28	56864	62725
leadframe	non noble metal	nickel	7440-02-0	0.100	19.42	19.42	194153	194153
wire	noble metal	gold	7440-57-5	0.005	0.88	0.88	8784	8784
encapsulation	organic material	carbon black	1333-86-4	0.004	0.70		6969	
	plastics	epoxy resin	-	0.049	9.41		94092	
	inorganic material	silicondioxide	60676-86-0	0.308	59.57	69.68	595913	696974
leadfinish	noble metal	gold	7440-57-5	0.010	1.87	1.87	18682	18682
plating	noble metal	gold	7440-57-5	0.010	1.87	1.87	18682	18682
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com